

8英寸全自动环切机器

8 INCH FULLY-AUTOMATIC RING DICING EQUIPMENT

AR6100RR

● 最大有效加工尺寸 (mm)

Maximum effective product size (mm)

ø8"

● 主轴配置方式

Configuration method of spindle

单主轴

Single-spindle



● 特点 FEATURE

四工位，多片协调加工，加工效率高。

Four-station, multi-piece coordinated processing, high processing efficiency.

兼容性好，与市面上的其他类型设备，关键耗材兼容性高。

Good compatibility with other types of equipment on the market and high compatibility with key consumables.

全自动上下料、传输定位、清洗、解胶、取环，实现全自动运行模式，大大降低OP工作量。

Fully automatic loading and unloading, transferring and positioning, cleaning, ungluing and ring taking, realizing fully automatic operation mode, greatly reducing OP workload.

稳定的TAIKO外环解胶和取环。

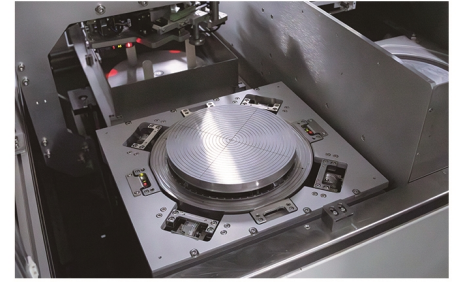
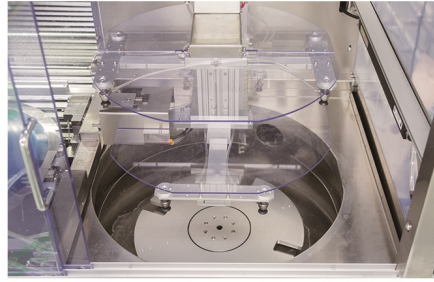
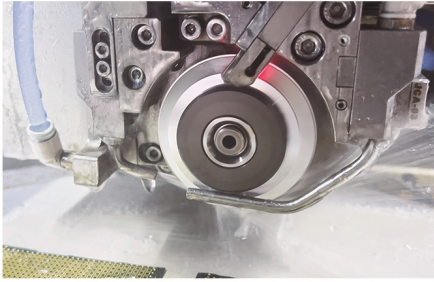
Stable TAIKO outer ring ungluing and ring removal.

定制化工作台设计，保证TAIKO工艺下晶圆特殊结构稳定加工。

Customized table design ensures stable processing of special structures of wafers under TAIKO process.

多轴联动环切技术，保证环切精度。

Multi-axis linkage circumferential cutting technology to ensure the precision of circumferential cut.



功能 FUNCTION

注: 「*」为选配功能, 支持个性化定制
PS: 「*」 is an optional feature that can be customized by the customer

掉环检测功能

Drop frame detection function

工作台自动清洗功能

Automatic clean of chuck table

智能UV解胶系统

Intelligent UV unglue

操作日志记录功能

Operation log

*工厂自动化模块

* Factory Automation Module

真空预警与真空管路去水功能

Vacuum warn and vacuum line de-water

搬运撞击检测功能

Handle detection

条形二维码识别功能

Bar QR code recognition

二流体清洗功能

Second fluid cleaning function

*软件定制

* Software Customization

参数 PARAMETER

主轴	Spindle	转速范围 (min-1)	Speed range (min-1)	3,000-60,000	
主轴	Spindle	最大刀片径 (mm)	Maximum blade diameter (mm)	Ø58	
主轴	Spindle	配置方式	Configuration method	单轴	single spindle
主轴	Spindle	输出功率 (kW)	Output power (kW)	1.8(2.4可选) at 30,000min-1	1.8(2.4 optional) at 30,000min-1
X轴	X-axis	可切割范围 (mm)	Cut range (mm)	310	
Y轴	Y-axis	可切割范围 (mm)	Cut range (mm)	310	
Y轴	Y-axis	单步步进量 (mm)	Single step step amount (mm)	0.0001	
Y轴	Y-axis	定位精度 (mm)	Position accuracy (mm)	0.003以内/310 0.002以内/5 (单一误差) Within 0.003 / 310 Within 0.002 / 5 (single error)	
Z轴	Z-axis	移动量分辨率 (mm)	Move volume resolution (mm)	0.00005	
Z轴	Z-axis	重复精度 (mm)	Repeat accuracy (mm)	0.001	
θ轴	θ-axis	最大旋转角度 (deg)	Maximum rotation angle (deg)	380	
主轴形式	Spindle type		单主轴, 安装硬盘做环形切割	Single spindle with hard cutter mounted for ring cut	
环切精度 (μm)	Ring cut accuracy (μm)		±50		
晶圆定位精度 (μm)	Wafer position accuracy (μm)		±50		
单片效率 (min/片)	Monolithic efficiency (min/piece)		9		
多片效率	Multi-slice efficiency		最多4片同时加工	Up to 4 pieces can be processed simultaneously	
设备重量 (kg)	Weight (kg)		≈2,800		
设备尺寸/W*D*H (mm)	Size / W*D*H (mm)		2,209*1,554*2,071		

应用 APPLICATION

